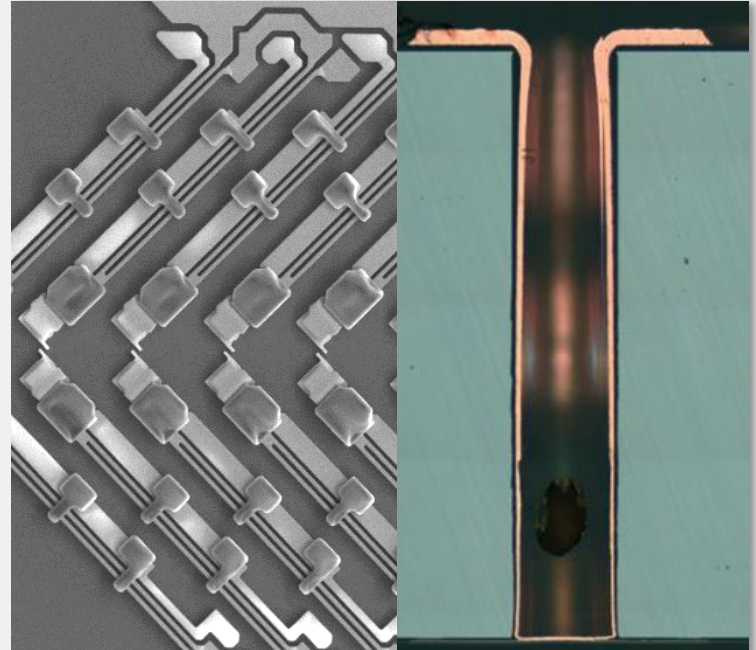


State-of-the-Art & Leading Edge

- Semiconductor processing: SiO_2 , Si_3N_4 , etc.
- Electroplating / electroless deposition
 - Ni, NiMn, NiFe, AuCo, PdNi, AuNi, Au, Ag, Pt, Cu, Ir, Sn, SnCu, SnBi, SnPb, In, Bi, Pd
 - Porosification, direct metallization
- Sputtering Au, Cu, Cr, Pt, Al, Ti, TiW, TiN
- Wet etching and dry etching
- Photolithography and polymer processing
 - Polyimide, BCB, SU8, AZ, dry resist, etc.
- Bonding & Packaging
- Rapid Thermal Processing
 - Silicidation, oxidation, annealing
- Injection molding and tool manufacturing
- Rapid prototyping / Additive manufacturing
 - FDM, SLA, 2PP
- CAD & machine shop services
- LASER cutting / drilling
- Fine line screen printing
- Nanoimprint
- Analysis and characterization
 - Profile, FIB, TEM, Auger spectroscopy, EDX, X-ray diffraction, etc.
- Mechanical property testing
 - Indentation, tensile test, etc.
- Reactive multilayers for packaging

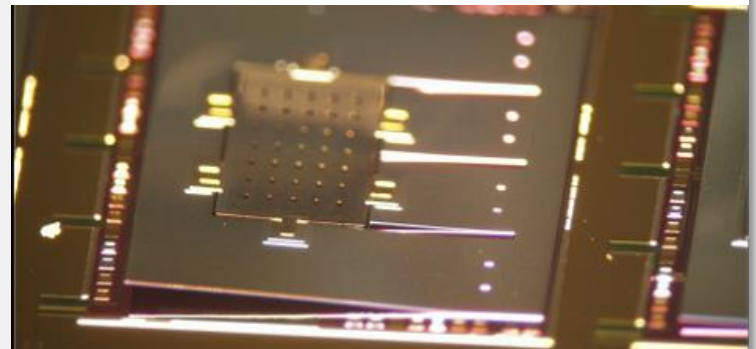


Ignition of electroplated reactive multilayer (Pd-Sn)



Programmable MEMS switch

Deep Si-via coating



For

- Volumes ranging from R&D, prototyping to mass production
- Substrates:
 - Semiconductor: 100 mm, 150 mm, 200 mm
 - Solar cells: 125 mm x 125 mm
156 mm x 156 mm

Applications

- Solar industry
- Microsystems & semiconductors
- Medical devices

